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TECHNICAL REPORT



Photonic integrated circuits – Part 1: Introduction and roadmap for standardization

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PHOTONIC INTEGRATED CIRCUITS –

Part 1: Introduction and roadmap for standardization

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IEC TR 62072-1, which is a Technical Report, has been prepared by subcommittee 86C: Fibre optic systems and active devices, of IEC technical committee 86: Fibre optics.

The text of this Technical Report is based on the following documents:

Enquiry draft	Report on voting
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Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 63072-1 series, published under the general title *Photonic integrated circuits*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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PHOTONIC INTEGRATED CIRCUITS –

Part 1: Introduction and roadmap for standardization

1 Scope

This part of IEC 63072, which is a Technical Report, provides an introduction to photonic integrated circuits (PICs) and describes a roadmap for the standardization of PIC technology over the next decade.

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2 Normative references

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